### **Complementary Silicon Plastic Power Transistors**

Designed for use in general purpose amplifier and switching applications.

### Features

- High Current Gain Bandwidth Product
- Compact TO-220 Package
- These Devices are Pb-Free and are RoHS Compliant\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit			
Collector – Emitter Voltage TIP31G, TIP32G TIP31AG, TIP32AG TIP31BG, TIP32BG TIP31CG, TIP32CG	V <sub>CEO</sub>	40 60 80 100	Vdc			
Collector–Base Voltage TIP31G, TIP32G TIP31AG, TIP32AG TIP31BG, TIP32BG TIP31CG, TIP32CG	V <sub>CB</sub>	40 60 80 100	Vdc			
Emitter-Base Voltage	V <sub>EB</sub>	5.0	Vdc			
Collector Current – Continuous	Ι <sub>C</sub>	3.0	Adc			
Collector Current – Peak	I <sub>CM</sub>	5.0	Adc			
Base Current	I <sub>B</sub>	1.0	Adc			
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	PD	40 0.32	W W/°C			
Total Power Dissipation @ $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub>	2.0 0.016	W W/°C			
Unclamped Inductive Load Energy (Note 1)	E	32	mJ			
Operating and Storage Junction Tem- perature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1.  $I_C = 1.8 \text{ A}, L = 20 \text{ mH}, P.R.F. = 10 \text{ Hz}, V_{CC} = 10 \text{ V}, R_{BE} = 100 \Omega$ 

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	62.5	°C/W
Thermal Resistance, Junction-to-Case	R <sub>0JC</sub>	3.125	°C/W

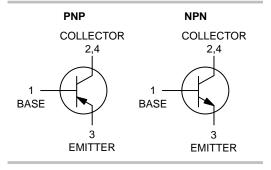
\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

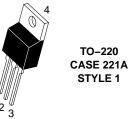


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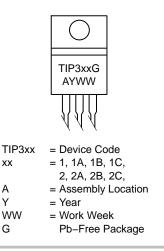
www.onsemi.com

### 3 AMPERE POWER TRANSISTORS COMPLEMENTARY SILICON 40–60–80–100 VOLTS, 40 WATTS





### MARKING DIAGRAM



### ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

Symbol	Min	Max	Unit
V <sub>CEO(sus)</sub>	40 60 80 100	- - -	Vdc
ICEO	-	0.3 0.3	mAdc
ICES	- - -	200 200 200 200	μAdc
I <sub>EBO</sub>	_	1.0	mAdc
h <sub>FE</sub>	25 10	_ 50	-
V <sub>CE(sat)</sub>	-	1.2	Vdc
V <sub>BE(on)</sub>	_	1.8	Vdc
f <sub>T</sub>	3.0	_	MHz
h <sub>fe</sub>	20	_	-
	ICEO ICES ICES IEBO IEBO VCE(sat) VBE(on) fT	$\begin{array}{c c c c c c c } & 40 \\ & 60 \\ & 80 \\ 100 \\ \hline \\ & & - \\ &$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

#### ECTRICAL CHARACTERISTICS 2500 ~1 h ۲۳

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2.0%.

TIP31G, TIP31AG, TIP31BG, TIP31CG (NPN), TIP32G, TIP32AG, TIP32BG, TIP32CG (PNP)

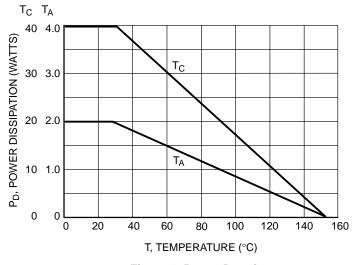
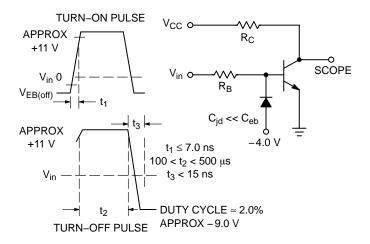
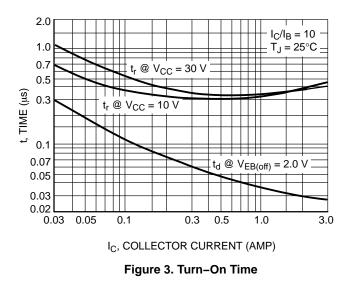


Figure 1. Power Derating



 $\mathsf{R}_\mathsf{B}$  and  $\mathsf{R}_\mathsf{C}$  VARIED TO OBTAIN DESIRED CURRENT LEVELS.

Figure 2. Switching Time Equivalent Circuit



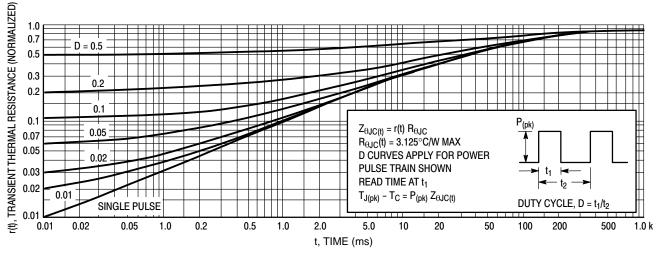


Figure 4. Thermal Response

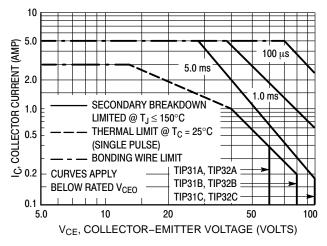
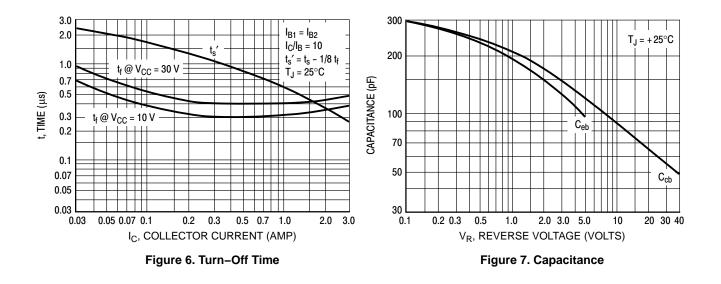
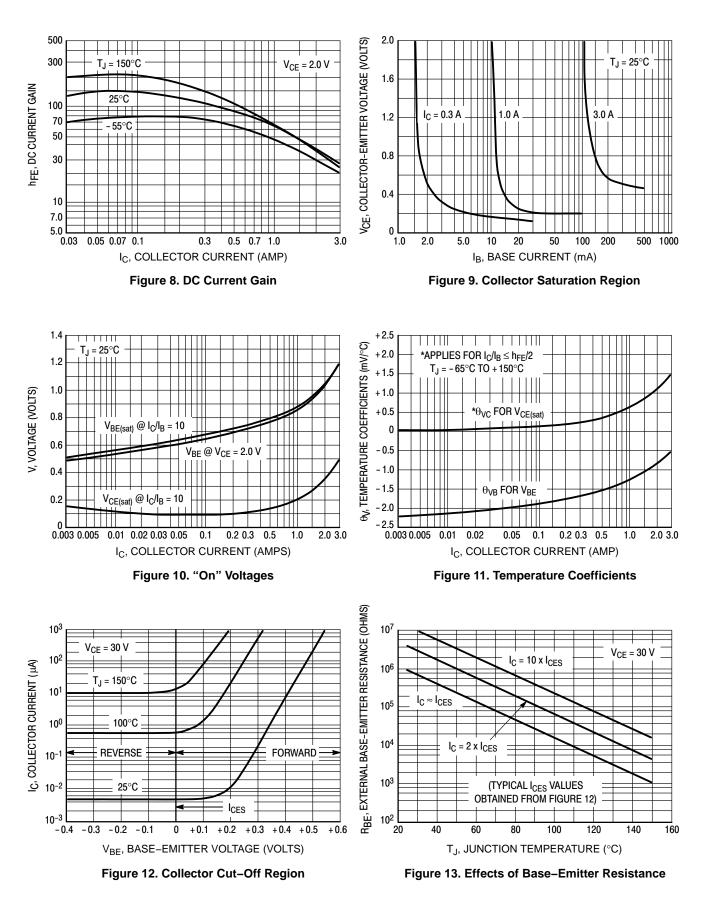


Figure 5. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on  $T_{J(pk)} = 150^{\circ}$ C;  $T_{C}$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}$ C.  $T_{J(pk)}$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.





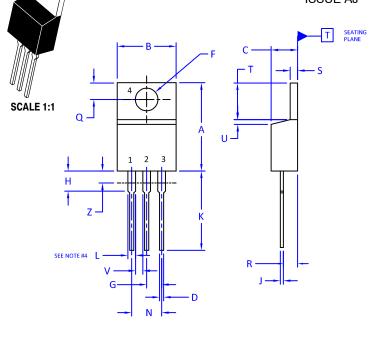
### **ORDERING INFORMATION**

Device	Package	Shipping	
TIP31G	TO-220 (Pb-Free)	50 Units / Rail	
TIP31AG	TO-220 (Pb-Free)	50 Units / Rail	
TIP31BG	TO-220 (Pb-Free)	50 Units / Rail	
TIP31CG	TO-220 (Pb-Free)	50 Units / Rail	
TIP32G	TO-220 (Pb-Free)	50 Units / Rail	
TIP32AG	TO-220 (Pb-Free)	50 Units / Rail	
TIP32BG	TO-220 (Pb-Free)	50 Units / Rail	
TIP32CG	TO-220 (Pb-Free)	50 Units / Rail	

DATE 05 NOV 2019



**TO-220** CASE 221A-09 ISSUE AJ



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.

2. CONTROLLING DIMENSION: INCHES

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
А	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1: PIN 1. 2. 3. 4.	COLLECTOR EMITTER	STYLE 2: PIN 1. 2. 3. 4.	EMITTER	3.	CATHODE ANODE GATE ANODE	STYLE 4: PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE MAIN TERMINAL 2
STYLE 5: PIN 1. 2. 3. 4.	DRAIN SOURCE	2. 3.	ANODE CATHODE ANODE CATHODE	2. 3.	CATHODE ANODE CATHODE ANODE	STYLE 8: PIN 1. 2. 3. 4.	
STYLE 9: PIN 1. 2. 3. 4.	COLLECTOR EMITTER	STYLE 10: PIN 1. 2. 3. 4.	GATE SOURCE DRAIN	STYLE 11: PIN 1. 2. 3. 4.	DRAIN SOURCE GATE	STYLE 12 PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE NOT CONNECTED

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DESCRIPTION: TO-220		PAGE 1 OF 1			
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